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PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ravi Kanth KOLAN	05/23/2008
Hao LIU	05/23/2008
Chin Hock TOH	05/23/2008

RECEIVING PARTY DATA

Name:	United Test and Assembly Center Ltd.
Street Address:	5 Serangoon North Avenue 5
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	554916

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13244630

CORRESPONDENCE DATA

Fax Number: 6568462005

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: +65 9836 9908

Email: oa.notification@horizonip.com.sg

Correspondent Name: Horizon IP Pte Ltd.

Address Line 1: 7500A Beach Road, #04-306/308

Address Line 2: The Plaza

Address Line 4: Singapore, SINGAPORE 199591

ATTORNEY DOCKET NUMBER:	UTAC P 2007 NAT 33 US 1
NAME OF SUBMITTER:	Dexter CHIN

Total Attachments: 4

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PATENT REEL: 029727 FRAME: 0335 ASSIGNMENT

For good and valuable consideration, we, Ravi Kanth KOLAN, residing at Blk 153,

Serangoon North Avenue 1, #04-526, Singapore 550153, a citizen of India; Hao LIU,

residing at No. 387, Ang Mo Kio Avenue 2, Singapore 567849, a citizen of Singapore; Chin

Hock TOH, residing at Blk 288A, Jurong East Street 21, #14-356, Singapore 601288, a

citizen of Malaysia;

Hereby sell, assign, and transfer to United Test and Assembly Center Ltd., a

corporation of Singapore, having its principal place of business at 5 Serangoon North

Avenue 5, Singapore 554916,

hereinafter "Assignee", its successors, assigns and legal representatives, the entire

right, title and interest in and for the United States and all foreign countries, in and to any and

all improvements which are disclosed in the application for United States Letters Patent,

which has been executed by the undersigned concurrently here within, and is entitled:

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and in and to said application and all divisional, continuing substitute, renewal, reissue, and

all other applications for Letters Patent which have been or shall be filed in the United States

and all foreign countries on any of said improvements; and in and to all original and reissued

patents which have been or shall be filed in the United States and all foreign countries on said

improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements

in its own name, and that, when requested, without charge to but at the expense of said

Assignee, their successors, assigns, and legal representatives to carry out in good faith the

intent and purpose of this agreement, the undersigned will execute all divisional, continuing

substitute, renewal, reissue, and all other patent applications on any and all said

improvements; execute all rightful oaths, assignments, powers of attorney and other papers;

PATENT

REEL: 029727 FRAME: 0336

communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

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23 May 2008

(Signature)

Ravi Kanth KOLAN

Witness:

(Signature)

ALICIA SIM

(Print name)

Date:

May 23, 08 1

(Signature)

Hao <u>LIU</u>

Witness:

(Signature)

ALICIA SIM

(Print name)

Date:

23 May 2008

(Signature)

Chin Hock **TOH**

Witness:

(Signature)

ALICIA SIM
(Print name)